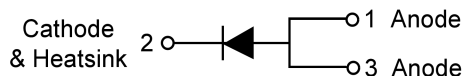
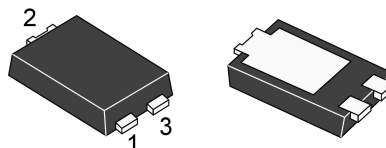


Features

- Schottky Barrier Chip
- High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Fow Power Loss,High Efficiency
- Excellent High Temperature Stability
- Plastic material-UL flammability 94V-0

Mechanical Data

- Case: TO-277B, molded plastic
- Terminals:Plated Leads Solderable per MIL-STD-202,Method 208
- Polarity:Cathode Band
- Mounting Position:Any
- Marking:Type Number
- Lead Free:For RoHS/Lead Free Version

TO-277B

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Ratings at 25°C ambient temperature unless otherwise specified ,Single phase ,half wave ,resistive or inductive load. For capacitive load,derate by 20%.)

		Symbols	SB 1020L	SB 1030L	SB 1045L	SB 1050L	SB 1060L	SB 1080L	SB 10100L	SB 10150L	SB 10200L	Units
Maximum repetitive peak reverse voltage		V _{RRM}	20	30	45	50	60	80	100	150	200	Volts
Maximum RMS voltage		V _{RMS}	14	21	31	35	42	56	70	105	140	Volts
Maximum DC blocking voltage		V _{DC}	20	30	45	50	60	80	100	150	200	Volts
Maximum average forward rectified current (see Fig.1)		I _(AV)	10.0									Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)		I _{FSM}	150.0									Amps
Maximum instantaneous forward voltage at 10.0 A(Note 1)		V _F	0.48			0.62		0.72		0.85		Volts
Maximum instantaneous reverse current at rated DC blocking voltage(Note 1)	T _a = 25°C	I _R	0.2									mA
	T _a = 125°C		15			50						
Typical thermal resistance (Note 2)		R _{θJC}	2.5									°C/W
Operating junction temperature range		T _J	-65 to +150									°C
Storage temperature range		T _{STG}	-65 to +150									°C

Notes: 1.Pulse test: 300 μ s pulse width,1% duty cycle

2.Thermal resistance from junction to case

FIG.1-FORWARD CURRENT DERATING CURVE

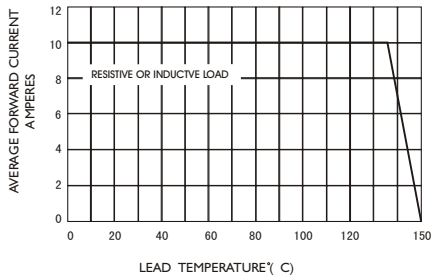


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

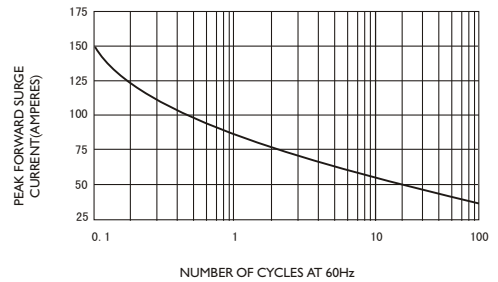


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

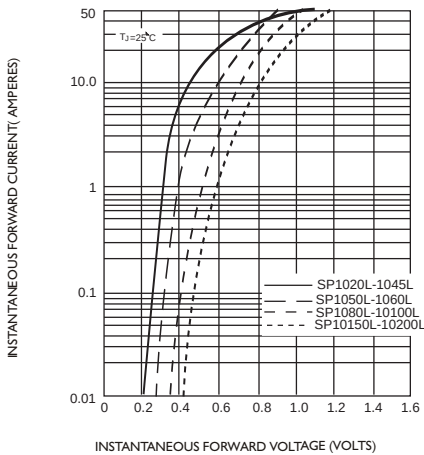


FIG.4-TYPICAL REVERSE CHARACTERISTICS

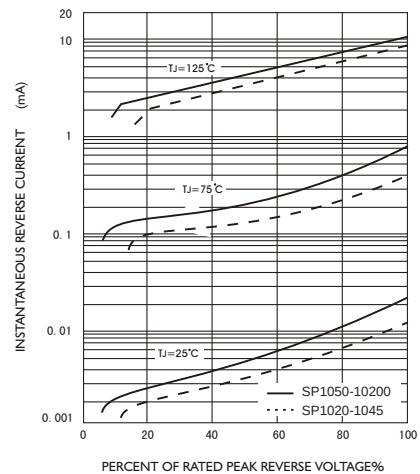


FIG.5-TYPICAL JUNCTION CAPACITANCE

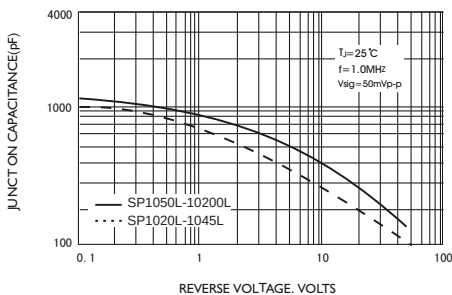
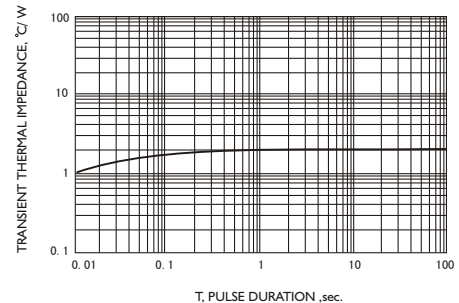
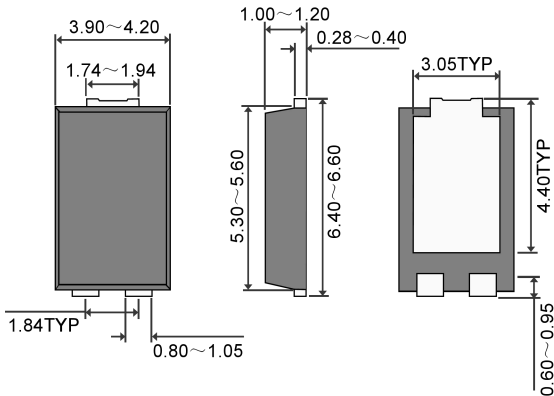


FIG.6-TYPICAL TRANSIENT THERMAL IMPEDANCE

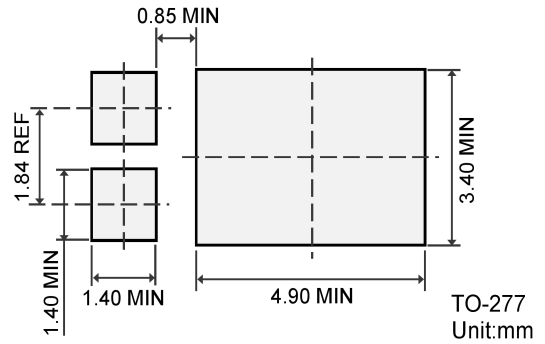


Package Outline Dimensions

Suggested Solder Pad Layout



TO-277
Unit:mm



Packing Information

Packaging	Package	Reel Quantity	Reel Size	Tape Size
Reel	TO-277B	5000 pcs	13'	12 mm

